

**3.0A Low VF Surface Mount Schottky
Barrier Rectifiers**

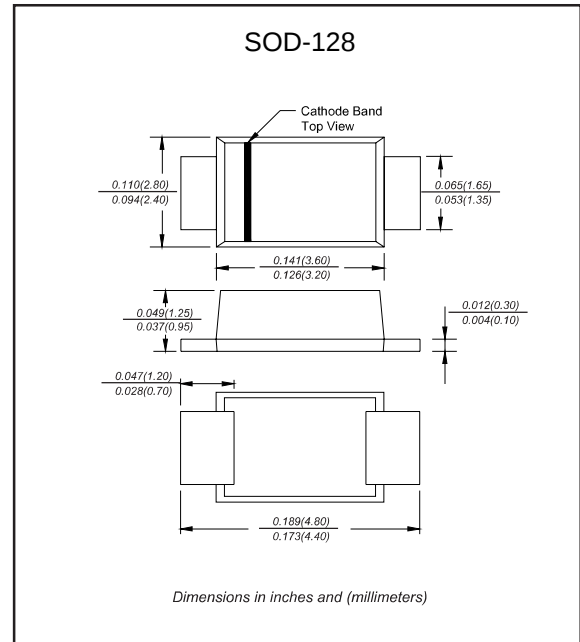
Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
250°C/10 seconds at terminals
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free

Mechanical data

- ◆ **Case**: JEDEC SOD-128 molded plastic body
- ◆ **Terminals**: Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity**: Color band denotes cathode end
- ◆ **Mounting Position**: Any

Package outline

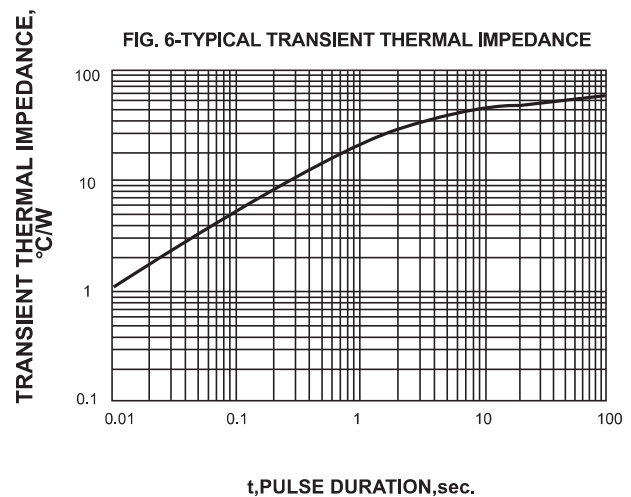
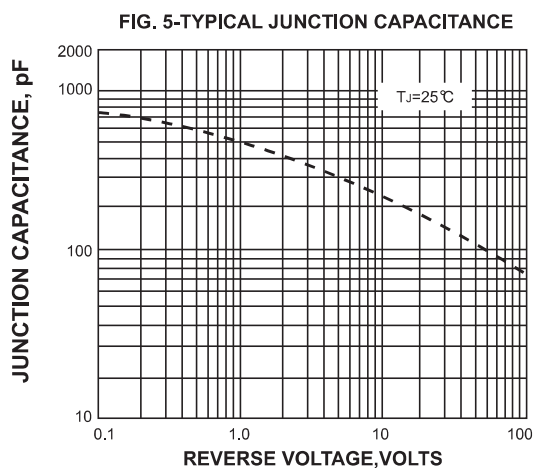
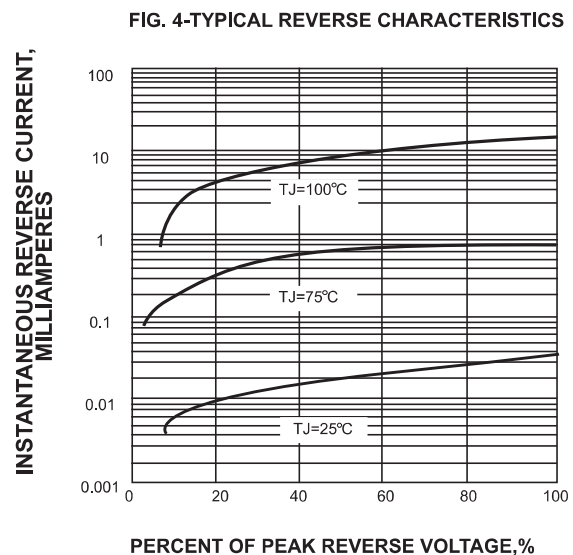
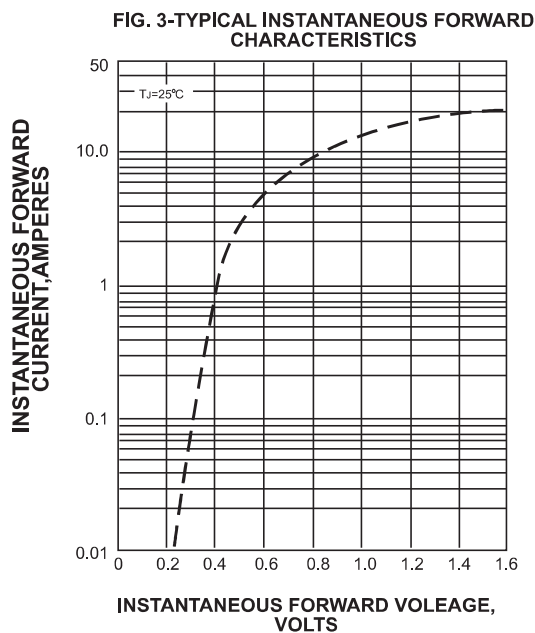
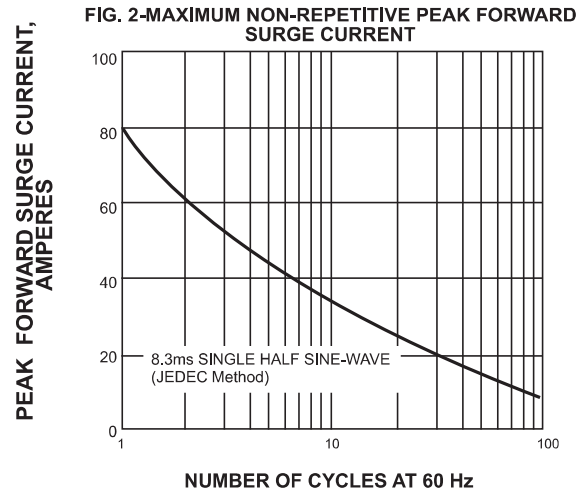
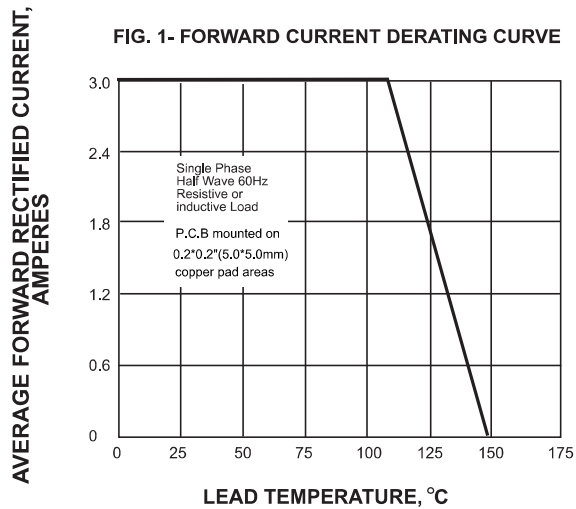


Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	PMEG6030EPF	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	60	V
Maximum RMS voltage	V_{RMS}	42	V
Maximum DC blocking voltage	V_{DC}	60	V
Maximum average forward rectified current at T_L (see fig.1)	$I_{(AV)}$	3.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	80.0	A
Maximum instantaneous forward voltage at 3.0A	V_F	0.53	V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	I_R	0.2 20.0	mA
Typical junction capacitance (NOTE 1)	C_J	28	pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	55	$^\circ\text{C/W}$
Operating junction temperature range	T_{JL}	-55 to +150	$^\circ\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

Rating and characteristic curves



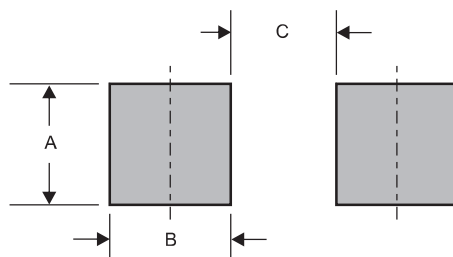
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking
PMEG6030EPF	AB

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-128	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)